Top Fabrication (Scale 1:1)

Layer Stack Legend

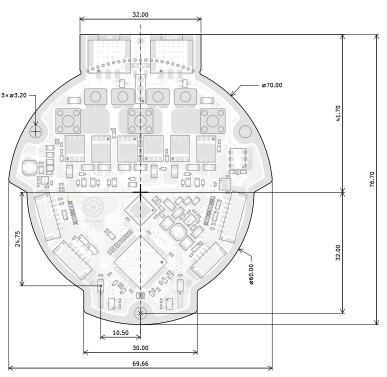| Material	Layer	Thickness	Dielectric Material	Type	Gerber
	F.Paste			Paste Mask	GBR
	F.Silkscreen			Legend	GBR
	F.Mask		Solder Resist	Solder Mask	GBR
Copper	**L1 (Sig, PWR)**	0.07mm (2oz)		**Signal**	GBR
Prepreg		0.18mm	FR−4	Dielectric	
Copper	**L2 (GND)**	0.035mm (1oz)		**Internal Plane**	GBR
Core		0.4mm	FR−4	Dielectric	
Copper	**L3 (Sig, PWR)**	0.035mm (1oz)		**Signal**	GBR
Prepreg		0.18mm	FR−4	Dielectric	
Copper	**L4 (Sig, PWR)**	0.035mm (1oz)		**Signal**	GBR
Core		0.4mm	FR−4	Dielectric	
Copper	**L5 (GND)**	0.035mm (1oz)		**Internal Plane**	GBR
Prepreg		0.18mm	FR−4	Dielectric	
Copper	**L6 (Sig, PWR)**	0.07mm (2oz)		**Signal**	GBR
	B.Mask		Solder Resist	Solder Mask	GBR
	B.Silkscreen			Legend	GBR
	B.Paste			Paste Mask	GBR

Total thickness: 1.62mm

Note: external layer thicknesses are specified after plating.

FABRICATION NOTES (UNLESS OTHERWISE SPECIFIED)

1) OUTLINE DEFINED IN SEPARATE GERBER FILE WITH "Edge_Cuts.GBR" SUFFIX.
   DIMENSIONS OF CIRCUMSIZED RECTANGLE SHOWN ON THIS DWG FOR REF ONLY.

2) SEE SEPARATE DRILL FILES WITH ".DRL" SUFFIX FOR HOLE LOCATIONS.
   SELECTED HOLE LOCATIONS SHOWN ON THIS DWG FOR REF ONLY.

3) IMPEDANCE CONTROL REQUIRED.
   Microstrip 100−Ohm Differential (L1 ref. L2)
   0.2032mm width, 0.28mm spacing

4) CONFIRM TRACE WIDTHS AND SPACINGS.

5) DESIGN GEOMETRY MINIMUM FEATURE SIZES:
   TRACE WIDTH   0.20 mm
   TRACE TO TRACE   0.20 mm
   MIN. HOLE (PTH)   0.25 mm
   MIN. HOLE (NPTH)   0.70 mm
   ANNULAR RING   0.15 mm
   COPPER TO HOLE   0.254 mm
   COPPER TO EDGE   0.25 mm
   HOLE TO HOLE   0.254 mm

All dimensions are in millimeters unless otherwise specified.